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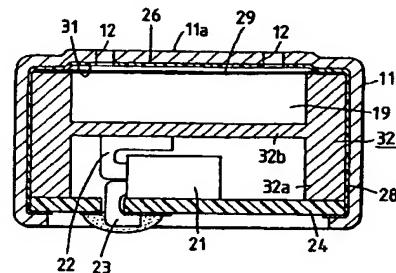
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⑤4 **Electret condenser microphone unit.**

⑤7 A n electret film (26) is formed on the rear side of a front face plate (11a) of a cylindrical capsule (11) made of aluminium. Closely in opposition thereto, an electrically conductive diaphragm (29) is held by an electrically conductive holding member (32) itself and disposed. By means of a wiring board (24) provided behind the holding member, the rear end of the capsule is closed. The rear end of the capsule is bent on the rear periphery of the wiring board, and calked thereat. In the capsule, an impedance conversion IC device (21) is connected to the electrically conductive holding member and the wiring board.

FIG. 3



BACKGROUND OF THE INVENTION

The present invention relates to a condenser microphone unit using an electret.

Fig. 1 depicts a conventional front electret condenser microphone unit. On the front side of a cylindrical capsule 11 of aluminium, a front face plate 11a is formed integrally, in which a second hole 12 is formed and a cloth 13 is attached on the front side of the front face plate 11a. A diaphragm support metal ring 14 is provided on the peripheral portion on the inner side of the front face plate 11a in opposition thereto, and electrically connected thereto. On the other surface of the metal ring 14, opposite to the surface thereof with the front face plate 11a, an electret diaphragm 15 is stuck. The electret diaphragm 15 comprises a polymer film, for example, a rather thick FEP (Fluoro Ethylene Propylene) film of 12.5 μm , on one side of which a metal is vapor deposited. The polymer film which is polarized is supported at its periphery by the metal ring 14.

A back electrode 17 is disposed to oppose the diaphragm 15, in close vicinity thereto, via a ring-shaped spacer 16, and the back electrode 17 is held on the front end of a cylindrical back electrode holding member 18. In a back chamber 19 comprised of an interior of the back electrode holding member 18, an impedance conversion IC device 21 is disposed. An input terminal 22 of the IC device 21 is connected to the back electrode 17. An output terminal 23 and a common terminal (not illustrated) are protruded from the rear side of the capsule 11, and connected to a wiring on a wiring board 24 that closes the rear side of the capsule 11. On the rear side of the wiring board 24, a rear end portion of the capsule 11 is bent so that each inner part is pressed against the front face plate 11a for fixing the entire assembly.

Fig. 2 depicts a conventional back electret type condenser microphone unit. Although the diaphragm itself of the front electret type of Fig. 1 comprises an electret, the back electret type of Fig. 2 is composed of an electret polymer film 26 attached closely to the upper side of the back electrode 17. More explicitly, an electret polymer film, for example, a FEP film is melted to adhere on the upper side of the back electrode 17, and polarized to form an electret. Other details of the composition are the same as those in Fig. 1.

With conventional electret condenser microphone units shown in Figs. 1 and 2, the back electrode 17 is required in addition to the other various parts. Therefore, it is difficult to assemble the unit automatically, resulting in a limited degree of cost reduction. Because an electret film is used as a diaphragm, there is a limit to make it thinner and therefore, the sensitivity cannot be made high-

er in excess of a limit.

SUMMARY OF THE INVENTION

An object of the present invention is to provide an electret condenser microphone unit which can be easily assembled automatically with a small number of parts and which has a high sensitivity.

According to the present invention, an electret polymer film is attached to the inner surface of a front face plate in a capsule. With a narrow spacing to said polymer film, an electrically conductive diaphragm is disposed in opposition thereto. The fringe portion of said electrically conductive diaphragm is held by an electrically conductive holding member, and connected electrically thereto. A wiring board is provided so that the rear side of the capsule is closed. An impedance conversion IC device disposed in the capsule is connected to the wiring board, and also connected to the holding member.

BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 is a sectional view of a conventional front electret type microphone;

Fig. 2 is a sectional view of a conventional back electret type microphone;

Fig. 3 is a sectional view of an embodiment of a microphone according to the present invention;

Fig. 4A is a view for explaining the manufacturing process of the capsule 11 in Fig. 3;

Fig. 4B is a view for explaining the manufacturing process of the capsule 11 in Fig. 3;

Fig. 4C is a view for explaining the manufacturing process of the capsule 11 in Fig. 3;

Fig. 5 is a sectional view of the second embodiment of the microphone according to the present invention;

Fig. 6 is a graph depicting sensitivity vs. frequency characteristics of the microphone in Fig. 6;

Fig. 7 is a sectional view of the third embodiment of the microphone according to the present invention;

Fig. 8A is a sectional view of another embodiment of the microphone according to the present invention;

Fig. 8B is a disassembly oblique view of the capsule 11 in Fig. 7;

Fig. 9 is a sectional view of another embodiment of the microphone according to the present invention;

Fig. 10A is a sectional view of another embodiment of the microphone according to the present invention;

Fig. 10B is a surface conductor pattern view of the wiring board in Fig. 10A;

Fig. 10C is a rear side conductor pattern view of the wiring board in Fig. 10A;

Fig. 11 is a sectional view for showing another modified embodiment of Fig. 10A;

Fig. 12 is a sectional view depicting another modified embodiment of Fig. 10A;

Fig. 13A is a sectional view for indicating still another modified embodiment of Fig. 10A;

Fig. 13B is an oblique view of the capsule 11 in Fig. 13A;

Fig. 14A is a sectional view of another embodiment of the microphone according to the present invention;

Fig. 14B is a front part view of the front face plate 11a, for showing the surroundings of the slits 64 composing the sound hole of Fig. 14A;

Fig. 15 is a sectional view of a capsule depicting another construction of the slits 64;

Fig. 16 is a sectional view of a capsule depicting still another construction of the slits 64; and

Fig. 17 is a sectional view of a capsule showing another construction of the slits 64.

DETAILED DESCRIPTION OF THE INVENTION

Fig. 3 depicts a first embodiment of the present invention in which parts corresponding to those in Fig. 1 are identified by the same numerals. In this embodiment, an electret polymer film 26 is stuck on the inner surface of the front plate 11a of the capsule 11. For instance, as shown in Fig. 4A, a polymer film, e.g. FEP film 28 is thermally melted evenly into a thickness of about 12.5 - 25 μm on one entire surface of an aluminium plate 27 of 0.3 - 0.35 mm in thickness. The aluminium plate 27 may advantageously be of JIS: A1100P, which is produced through annealing at 340°C to 410°C by air or in the furnace, and which is excellent in mildness and easy pressing in a later manufacturing process. In addition, it is also preferable that an oxide film is formed on the surface of the aluminium plate by a chemical processing so that the bonding force of the polymer film 26 is greater. It is also possible to make the bonding force of the polymer film 26 larger by treating the surface of the polymer film to be adhered, through a corona discharging process. The polymer film 26 can be continuously melted onto said aluminium plate 27, using a heat pressing roll.

The aluminium plate 27 with said polymer film 26 stuck thereon is cupped by pressing with reducing dies, into the capsule 11 with the FEP film 28 equipped inside thereof as shown in Fig. 4B. At the same time, the polymer film 26 in the rear end fringe of the capsule is peeled by about 0.8 mm to expose a base metal of aluminium. And, a sound hole 12 is formed commonly through the front face plate of the capsule 11 and the FEP film 28. Next,

a part of the FEP film 28 stuck on the inside of the front face plate 11a of the capsule 11 is polarized by an electron beam, thereby obtaining an electret polymer film 26 as shown in Fig. 4C.

Fig. 3 is now explained again. An electrically conductive diaphragm 29 is disposed in opposition to the electret polymer film 26 to define a narrow spacing such as 25 to 40 μm therebetween, except for a peripheral portion. The electrically conductive diaphragm 29 can for instance comprise an extremely thin 2 to 4 μm PET (polyester) film or polyphenylene sulfide (PPS) film on one side of which Ni or Al, etc. is vapor deposited to form an electrically conductive layer. The front face panel 11a is slightly pressed forward except for the peripheral portion thereof, thus creating a shallow recess 31. In the fringe portion of the electret polymer film 26, a peripheral portion of the electrically conductive diaphragm 29 is disposed in opposition thereto and in contact therewith. Hence, an air gap is formed in between the electret polymer film 26 and the electrically conductive diaphragm 29, corresponding to the depth of the recess 31. Although the recess 31 is not illustrated in Fig. 4B or 4C, it is formed beforehand when the capsule is manufactured by pressing.

The electrically conductive holding member 32 is housed in the capsule 11 and holds the electrically conductive diaphragm 29 on the front end of the electrically conductive holding member 32. In addition, they are electrically connected with each other, that is, the electrically conductive layer of the electrically conductive diaphragm 29 is opposed to and made in contact with the electrically conductive holding member 32. In addition, a back chamber 19 is composed of the electrically conductive holding member 32 on the rear side of the electrically conductive diaphragm 29. The electrically conductive holding member 32 is formed by for example a metal casting which consists of a cylindrical portion 32a engaged with the capsule 11 and a partition portion 32b that divides the interior thereof into front and rear spaces. The front side of said electrically conductive holding member 32 is coated with an epoxy base electrically conductive adhesive which bonds the tensioned diaphragm 29 on its electrically conductive layer side thereof. A back chamber 19 is defined by a space between the partition portion 32b and the electrically conductive diaphragm 29. Since the polymer film 28 is covered on the inner peripheral surface of the capsule 11, the electrically conductive holding member 32 is electrically insulated from the capsule 11.

The rear side of the capsule 11 is closed by the wiring board 24. In this embodiment, the wiring board 24 is disposed in opposition to and in contact with the rear end of the electrically conductive

holding member 32, while a rear end portion of the capsule 11 is bent to push and fix the holding member 32 and the wiring board 24 against the front face plate 11a. In between the wiring board 24 and the partition portion 32b, an impedance conversion IC device 21 is disposed and the input terminal 22 of the IC device 21 is connected to the partition portion 32b. An output terminal 23 and a common terminal (not illustrated) are led to the outside of the wiring board 24, and connected to an output wiring and a common wiring, respectively. Furthermore, a bent inner end fringe of the capsule 11 is connected to the common wiring in the rear periphery of the wiring board 24.

According to the construction described above, the diaphragm 29 vibrates according to a sound signal coming from the front side while varying a static capacitance between the electrically conductive diaphragm 29 and the front face plate 11a, thus the equipment acts as a condenser microphone.

The electrically conductive diaphragm 29 may also comprise electrically conductive layers formed on both sides of the polymer film. In this case, both of these electrically conductive layers are electrically connected. The electrically conductive holding member 32 is not limited to such one that is formed entirely by a metal material, but can be formed of an insulation material shaped into a necessary form on which a metal layer is plated as an electrically conductive means. It is also possible to provide elevated portions in suitable intervals from the front face plate 11a to the holding member 32, while omitting the recess 31. A cloth may also be attached to the front side of the front face plate 11a.

Fig. 5 denotes a second embodiment of the electret condenser microphone according to the present invention, in which those parts corresponding to those of Fig. 3 are identified by the same numerals. The electrically conductive holding member 32 in use is short in the axial direction like the conventional metal ring 14 shown in Fig. 1. A cylindrical member 34 made of an insulation material, for example, ABS resin may also be intercalated in between the electrically conductive holding member 32 and the wiring board 24. In this case, a recess 35 is formed in the front end of the cylindrical member 34 in which the end portion of the input terminal 22 of the IC device 21 is disposed. In such a state as the end portion of said input terminal 22 protruding slightly forwardly of the front side of the cylindrical member 34, the cylindrical member 34 is pressed against the electrically conductive holding member 32, thus the input terminal 22 coming in contact with the electrically conductive holding member 32 while establishing electrical connection.

In the embodiment depicted in Fig. 5, the outer surface of the front face plate 11a of the capsule 11 is made flat instead of forming steps to create a recess 31, aiming at more beautiful appearance. The outer surface may be printed to prevent dazzling of the base metal of aluminium, or conditioned for easy clothing work. In addition, like in Fig. 3, the polymer film 28 in the rear end portion of the capsule 11 is removed at the same time as pressing the capsule 11, thereby exposing the base aluminium metal and calking the rear end portion of the capsule 11 onto the rear side of the wiring board 24. Thus, the capsule 11 is automatically connected to the common wiring in the rear periphery of the wiring board 24. The cylindrical member 34 in the illustration is such one that has the rear side thereof closed integrally. However, the rear side may also have an opening. In addition, the equipment can also be assembled more easily by encasing the holding member 32 with the diaphragm 29 retained, into the capsule 11 and then housing an assembly of the IC device 21, wiring board 24 and the cylindrical member 34 assembled beforehand, into the capsule 11.

By adequately selecting the diameter and number of sound holes 12 on the front face plate 11a of the capsule 11, it is possible to suppress creating a peak by a resonance frequency f_0 of the diaphragm 29 in a high-frequency range of the frequency characteristics as a microphone. For instance, in the case of using the capsule 11 of 9.3 mm in outer diameter and the diaphragm 29 of 7.0 mm in effective diameter, if five sound holes 12, each of 1.0 mm in diameter, or six sound holes, each of 0.8 mm in diameter, are formed in equal spacings on a circle of 3.5 mm in diameter around the axial center of the capsule 11, a peak is formed in a high-frequency range of the sensitivity vs. frequency characteristics as shown in the curve 36 of Fig. 6. However, where the number of 0.8 mm sound holes 12 reduced to 5, the peak in the high-frequency range no longer exists as shown in the flat curve 37. However, where the diameter of each sound hole 12 is made further smaller, for instance, five 0.6 mm sound holes or four 0.8 mm sound holes are provided, sensitivity in the high-frequency range becomes low in excess as shown by the curve 38. Therefore, an optimum case is that five sound holes of 0.8 mm each in diameter are formed.

Fig. 7 depicts a third embodiment of the present invention. As shown with the same numerals for parts corresponding to those of Fig. 5, the electrically conductive holding member 32 is shaped into a disk of which an inner part except for a periphery for holding the diaphragm 29 is constructed into a closure portion 32a recessed backwardly parallel to the diaphragm 29 while keeping a

very small spacing (for instance, 20 to 30 μm) to the diaphragm 29. The closure portion 32a closes the rear chamber 19 behind the holding member 32 and sound holes 39 are formed in said closure portion 32a. By appropriately selecting the diameter and number of the sound holes 39, it is possible to suppress the peak in the high-frequency band in the sensitivity vs. frequency characteristics of Fig. 6, while making the characteristic curve flat. In that case, the diameter of each sound hole 12 is made slightly larger, for instance 1.0 mm and five of them are formed to prevent an adverse affect to the frequency characteristics.

Referring to Figs. 5 and 7, it is also possible to omit the polymer film 28 on the inner side surface of the capsule 11 such that the electret polymer film 26 is bonded only to the front face plate 11a using an adhesive.

Figs. 8A and 8B depict a fourth embodiment of the present invention. With the present embodiment, as shown in Fig. 8A, no polymer film is formed on the inner side surface of cylindrical aluminium member 43. Also, the front face plate 11a on which the electret polymer film 26 is formed is manufactured as a separate disk 41 which is press fit into an aperture 43A formed in the front face of the cylindrical aluminium member 43. More explicitly, as shown in Fig. 8B, a FEP film 42 is attached by melting or sticking on one side of the circular aluminium plate 41. Sound holes 12 are then drilled and the FEP film 42 is polarized into an electret polymer film 26. As shown in Fig. 8A, the aluminium plate 41 is press fit into the front aperture of the cylindrical aluminium member 43, as an integrated body which comprises the capsule 11. Other details of the construction are similar to those of the embodiment of Fig. 5.

An embodiment modified from that of Figs. 8A and 8B is shown in Fig. 9 where a separate circular front face plate 11a (41) coated with an electret polymer film can also be disposed in the inside. More explicitly, an electret polymer film 26 is formed on one side of a circular aluminium plate 41 which has a thick periphery and an inner part formed into a recess 31, and the aluminium plate 41 is pressed from the inside of the capsule 11 against a front flange 43a of the cylindrical member 43 as shown in Fig. 9, and fixed thereto thus forming the capsule 11.

In the description above, it is also possible to compensate the variance of polarizing degrees in the products of the electret polymer film 26, by intercalating a spacer between the periphery of the diaphragm 29 and the electret polymer film 26. In this case, it is also possible that no recess 31 is formed but the front face plate 11a has the same thickness in the entirety.

With a conventional front electret type microphone shown in Fig. 1, the electret diaphragm 15 is used. Therefore, it is difficult to make the thickness thereof less than 12.5 μm . Hence, the sensitivity cannot be made higher than a corresponding limit, for instance, -45 dB at 1 KHz. According to the front electret type microphone of the present invention as described referring to the various embodiments above, the thickness can be made for instance as thin as 2 μm because the diaphragm 29 need not be an electret. As a result, in the arrangement of Fig. 5, the sensitivity can be made -38 dB at 1 KHz, as much as 7 dB higher than before. Consequently, S/N is also made higher than 45 dB, thus improving conventional products by 5 dB. Also with other front electret types according to the present invention, similar performance can be expected.

In addition, since the electret polymer film 26 is formed on the inner surface of the capsule, the thickness thereof can be made thicker, for instance 25 μm . Correspondingly, the variance of polarizing degrees of related products can be made smaller along with higher stability.

Relating to manufacturing, for instance, the embodiments shown in Figs. 5, 7, 8A, 9, etc., the impedance conversion IC device 21 is provided with an input terminal 22, output terminal 23 and a common terminal (not illustrated) for a lead wire. The output terminal 23 and the common terminal are inserted into lead wire entrance holes 24H penetrating the rear wall portion 34W of the cylindrical member 34 and the wiring board 24, and then the tips thereof are bent and soldered onto conductor patterns printed on the rear side of the wiring board. Such manufacturing processes as described above are required. However, it is difficult to automate these processes. Consequently, the construction is not suitable for automatically manufacturing and assembling microphone units. An embodiment improved in this regard is shown in Fig. 10A. With the embodiment of Fig. 10A, the wiring board in use comprises a double-sided wiring board 24'. In addition, the IC device 21 preferably is of a thin, chip type. In order to electrically connect the electrically conductive diaphragm 29 to the input terminal 22 of the IC device 21, a ring-shaped conductor pattern 51 is formed on the upper periphery of the double-sided wiring board 24' as shown in Fig. 10B. The rear end surface of the electrically conductive holding member 32 is coaxially stuck thereon. A conductor pattern 52 to which the input terminal 22 is to be soldered is formed extendedly from the ring-shaped conductor pattern 51. The conductor patterns 53 and 54 to which the output terminal 23 and the common terminal 23' of the IC device 21 are to be soldered, respectively, are connected to the conductor pat-

terns 55 and 56 on the rear side as shown in Fig. 10C, via the through-holes 53H and 54H, respectively. On the rear periphery of the wiring board 24', a ring-shaped conductor pattern 57 is formed in the same manner as with the embodiments described so far, while forming a common wiring pattern 58 extendedly from the ring-shaped conductor pattern 57. The conductor pattern 56 to be connected to the common terminal 23' of the IC device is actually connected to the common wiring pattern 58 via the ring-shaped conductor pattern 57. The section of the wiring board 24' in Fig. 10A is a section along the X-X line in Figs. 10B and 10C.

In a mass production line, the IC device 21 is automatically positioned at a predetermined location of each double-side wiring board 24' by a mounted machine, and soldered automatically with a solder reflow system. At that time, the through-holes are filled with a solder metal to prevent venting air out of the back chamber 19, via the through-holes.

A recess 31 is formed on the rear surface of the front face plate 11a, defining a spacing to the electrically conductive diaphragm 29 by means of a step difference to the outer fringe thereof. With the embodiment of Fig. 10A, a slit hole 12' (for instance, 0.4 mm in width and 2.0 mm in length) is formed at a center portion of the front face plate 11a, in place of a number of circular sound holes 12 constructed in the embodiments described thus far. To assemble the microphone unit of Fig. 10A, first the polymer film 28 is formed on the inner wall surface of the capsule 11, and the polymer film on the rear surface of the front face plate 11a is polarized into an electret polymer film 26. Next, the electrically conductive cylindrical holding member 32 that retains an electrically conductive diaphragm 29 is inserted, and then a double-side wiring board 24' with a mounted IC device 21 is inserted. Eventually, the rear end portion of the capsule 11 is caked and fixed. These processes of an assembling work can be easily automated.

Fig. 11 depicts an embodiment modified from the microphone unit of Fig. 10A, in which the electrically conductive diaphragm 29 is stuck to and fixed at the ring-shaped, electrically conductive holding member 32 while intercalating an electrically conductive cylindrical member 34' in between said electrically conductive holding member 32 and the double-side wiring board 24'. Other details of the structure are similar to those of Fig. 10A.

In the embodiment of Fig. 12, a ring-shaped spacer 16 is intercalated in between the electret polymer film 26 on the rear side of the front face plate 11a and the electrically conductive diaphragm 29, instead of forming a recess in the rear surface

of the front face plate 11a of the capsule 11. In addition, an electrically conductive cylindrical member 34' is disposed in between the electrically conductive diaphragm 29 and the double-side wiring board 24'. The electrically conductive diaphragm 29 is held by either the rear end surface of the spacer 16 or the front end surface of the electrically conductive cylindrical member 34'. By means of the spacer 16, a spacing between the electret polymer film 26 and the electrically conductive diaphragm 29 is regulated into specified dimensions. Other details of the composition are similar to those of Fig. 10A.

An embodiment modified from that of Fig. 12 is shown in Figs. 13A and 13B, in which a square area of the front face plate 11a of the capsule 11 is depressed inwardly. That is, it is pressed inwardly to form a step difference slightly greater than the thickness of the plate 11a so that opposite two edges of the depression are shared vertically to form narrow slits 61, while the other two edges form sloped continuous steps. Other details of the composition are similar to those in Fig. 10A. Since the narrow slits 61 are used as sound holes as described above, it is effectively prevented that dust or any foreign object enters the sound holes, thus the diaphragm 29 will be kept clean, so a cloth to be stuck on the front face plate 11a can be omitted. Furthermore, in the various embodiments as described so far, each sound hole 12 or 12' is formed in a plane parallel to the front face plate 11a. Therefore, when the capsule 11 is viewed from the front side, part of the electrically conductive diaphragm 29 is exposed outside. To the contrary, in the embodiment of Figs. 13A and 13B, the slits 61 are formed substantially vertical to the front face plate 11a. Consequently, the electrically conductive diaphragm 29 is not exposed, which brings about a higher electromagnetically shielding effect. Therefore, the embodiment realizes an advantage of a lower level of the induction noise applied to the electrically conductive diaphragm 29 connected to the high impedance input side of the impedance conversion device 21.

The embodiment depicted in Fig. 13A has been explained to have slits 61 which are formed by shearing two opposite sides of a pressed square recess in the front face plate 11a. It is also possible to provide a plurality of arc-shaped, sheared slits in equal angular spacings on the circumference of a circular pressed recess. Such an embodiment as described above is shown in Fig. 14A. On the rear side of the front face plate 11a of a cylindrical capsule 11 made of a metal such as aluminium, a circular region shown by a broken line 62R in Fig. 14B is recessed making the thickness thereof smaller than one half of the thickness of other parts, thus forming a thin-wall portion

62 beforehand. In a coaxial relationship with the circular thin-wall portion 62, a recess 63 of a circle 63R in a smaller diameter is formed by pressing the front face plate 11a from the front side thereof using a press machine. At that time, the thin-wall portion 62 is sheared on the circle 63R in equal angular intervals, while leaving a connection portion 65, thereby forming vertical slits 64.

For instance, the thickness of the front face plate 11a is 0.3 mm while the thickness of the thin-wall portion 62 formed by pressing the rear side thereof toward the front side is 0.1 mm. The rear side of the thin-wall portion 62 in the recess 63 is on the same plane as the rear side of the front face plate 11a. Therefore, the vertical gap "t" of the slits 64 becomes 0.1 mm. The diameter of the circular recess 63 is 3 mm. In such a manner as described above, slits 64 are formed perpendicular to the front face plate 11a and in between the outer side of the front face plate 11a and the rear side. Other details of the composition are similar to those in Fig. 11.

The embodiment of Fig. 14A relates to a case where the circular recess 62 is formed in the front side of the front face plate 11a. As shown in Fig. 15, the circular recess 63 can also be formed in the rear side of the front face plate 11a as shown in Fig. 15. In addition, the thin-wall portion 62 and the circular recess 63 may also be shaped rectangular or polygonal instead of circular.

Another method of forming slits 64 is that, instead of forming the thin-wall portion 62 as shown in Figs. 14A and 15, an inner portion of the front face plate 11a is pressed forward from the outer side while leaving connecting portions thereof in a tapered thin shape and shearing other portions to form vertically slits 64, as shown in Fig. 16. On the other hand, as shown in Fig. 17, a center portion of the front face plate 11a may be pushed inward thus forming vertical slits 64. Furthermore, slits may also be formed to extend in radial directions.

According to the present invention as described above, unlike a conventional microphone unit, at least no back electrode is needed and correspondingly, the number of required parts is smaller while facilitating automatic assembling. In the case that the spacer is also omitted in particular, the microphone unit according to the present invention is more suitable for automatic assembling.

Moreover, where a diaphragm of an electret is used in a conventional system, it is difficult to make the thickness less than 12.5 μm , which results in a correspondingly low sensitivity, namely -45 dB at 1 KHz. However, according to the present invention, the thickness of the diaphragm 29 can be made as thin as for instance 2 μm . According to the arrangement of Fig. 3, the sen-

sitivity can be improved to -38 dB at 1 KHz, that is, higher than the conventional limit as much as 7 dB. As a result, S/N also becomes more than 45 dB, namely 5 dB higher than those of conventional units.

Since the electret film 26 is formed on the inner surface of the capsule, the thickness thereof can be made larger, for instance 25 μm . Hence, the variance of polarizing degrees in products is correspondingly smaller and the stability of polarizing degrees is higher.

Claims

1. An electret condenser microphone unit comprising:
 - a cylindrical portion and a metal capsule having a front face plate that is disposed to close an end of said cylindrical portion and provided with a formed sound hole;
 - an electret polymer film attached on the rear side of said front face plate in said capsule;
 - an electrically conductive diaphragm disposed in close opposition to said polymer film with a spacing, in said capsule;
 - an electrically conductive holding means for holding a peripheral portion of said electrically conductive diaphragm in said capsule;
 - a wiring board for closing the rear side of said capsule; and
 - an impedance conversion IC device disposed in said capsule and connected to said electrically conductive holding means, said wiring board and said capsule.
2. The microphone unit of Claim 1, in which the rear end of said electrically conductive holding means is disposed in opposition to and in contact with said wiring board and composes a rear chamber by said electrically conductive holding means in the rear side of said electrically conductive diaphragm.
3. The microphone unit of Claim 1, in which a cylindrical insulation material is disposed in between said electrically conductive holding means and said wiring board and a rear chamber is composed in the rear side of said electrically conductive diaphragm, by said cylindrical insulation material.
4. The microphone unit of Claim 1, in which said cylindrical portion and said front face plate are formed integrally with each other, and a polymer film continued from said electret polymer film is coveringly attached to the inner peripheral surface of said cylindrical portion.

5. The microphone unit of Claim 4, in which the rear end of said cylindrical portion is bent toward and calked at the fringe of the rear side of said wiring board.
6. The microphone unit of Claim 5, in which a metal surface is exposed on the inner peripheral surface at the rear end of said cylindrical portion and is in contact with a conductor pattern formed on the rear side of said wiring board.
7. The microphone unit of Claim 4, in which a recess portion is formed on the rear side of said front face plate except for the fringe portion, and said electrically conductive holding means presses the fringe portion of said electrically conductive diaphragm held thereby, against the peripheral portion on the rear side of said front face plate.
8. The microphone unit of Claim 1 or 4, in which a cylindrical insulation material is intercalated in between said electrically conductive holding means and said wiring board, thereby a rear chamber is composed behind said electrically conductive diaphragm, and an input terminal of said impedance conversion IC device is connected to said electrically conductive holding means.
9. The microphone unit of Claim 8, in which said input terminal of said IC device is intercalated in between said electrically conductive holding means and said cylindrical material.
10. The microphone unit of Claim 1 or 4, in which the rear end of said electrically conductive holding means is backwardly extended in opposition to and in contact with said wiring board, thereby forming a rear chamber behind said electrically conductive diaphragm.
11. The microphone unit of Claim 1 or 4, in which a ring-shaped spacer is provided in between the fringe portion of the rear side of said front face plate and the peripheral portion of said electrically conductive diaphragm, and defines said spacing therebetween.
12. The microphone unit of Claim 1, in which said front face plate is formed separately from said cylindrical portion and is pressed into and fit in an aperture formed at the front end of said cylindrical portion.
13. The microphone unit of Claim 1, in which said cylindrical portion is provided with a flange

portion of which the front end is bent inwardly in the radial direction, and said front face plate is formed separately from said cylindrical portion and disposed in opposition to and in contact with the rear side of said flange portion.

14. The microphone unit of Claim 4, in which said wiring board is a double-sided wiring board on the upper side of which there are a peripheral conductor pattern in opposition to and in contact with the rear end surface of said electrically conductive holding means and an input terminal conductor pattern extended from said peripheral conductor pattern and connected to the input terminal of said IC device.
15. The microphone unit of Claim 14, in which the upper surface of said wiring board is provided with an upper surface output terminal conductor pattern connected to the output terminal of said IC device, and the rear surface of said wiring board is provided with a common conductor pattern to come in contact with the rear end portion bent inside said cylindrical portion and a rear surface output conductor pattern at least a part of which overlaps with said upper surface output terminal conductor pattern, and said upper and rear surface output conductor patterns are electrically connected together through a through hole formed in said wiring board.
16. The microphone unit of Claim 14, in which said electrically conductive holding means comprises an electrically conductive ring in opposition to and in contact with the peripheral portion of said electrically conductive diaphragm and an electrically conductive cylinder intercalated in between said electrically conductive ring and said wiring board.
17. The microphone unit of Claim 1, 4 or 14, in which said sound hole comprises a partially cut slit formed at an edge of a protrusion portion formed by pressing said front face plate, in a relationship substantially perpendicular to said front face plate.
18. The microphone unit of Claim 17, in which said protrusion portion is protruded, in a thin wall thickness zone where the wall thickness is made smaller by forming a recess portion on one side of said front face plate, from the other side to said one side of said front face plate.
19. The microphone unit of Claim 17, said protrusion portion protrudes from one side to the other side of said front face plate.

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FIG. 1
PRIOR ART

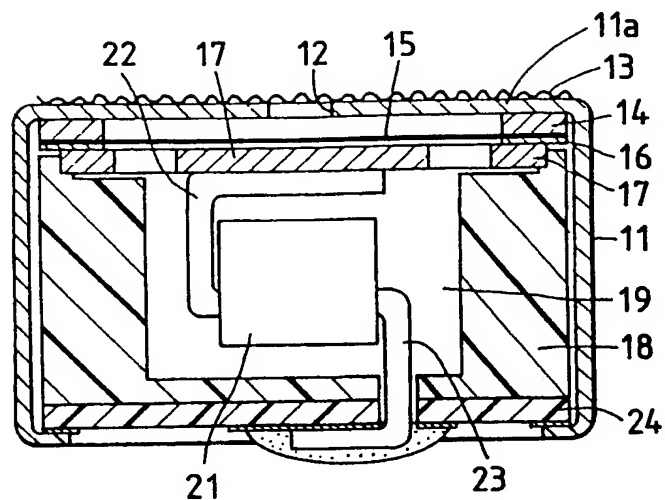


FIG. 2
PRIOR ART

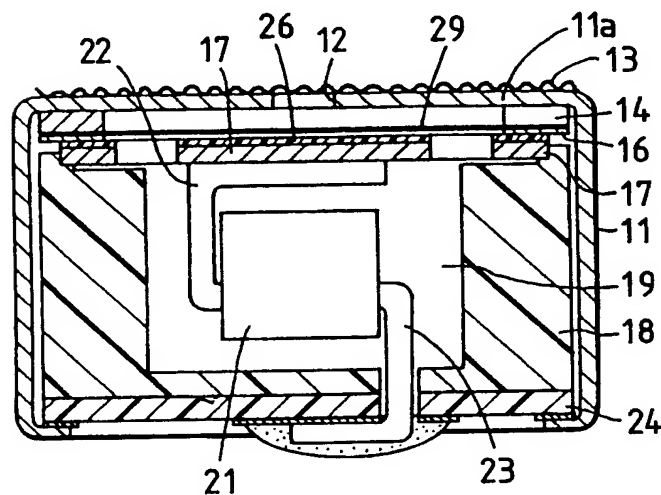
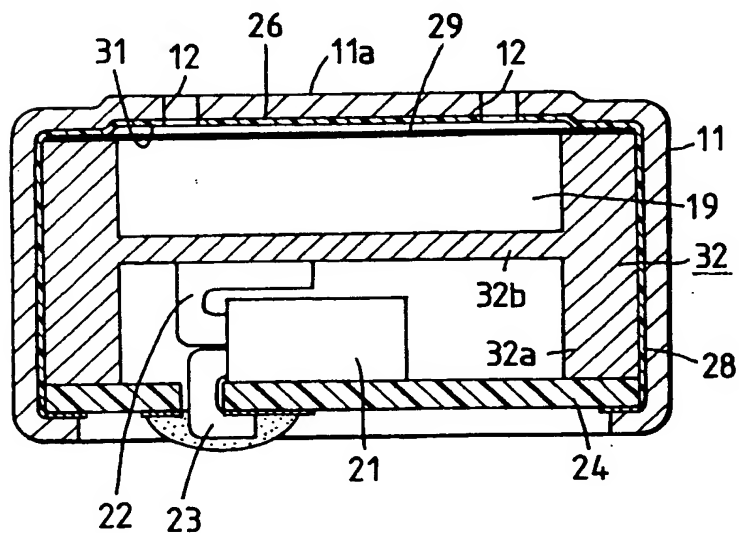


FIG. 3



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FIG. 4A

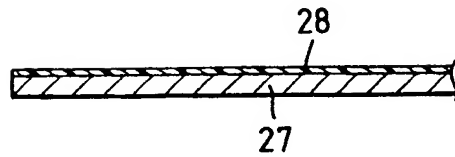


FIG. 4B

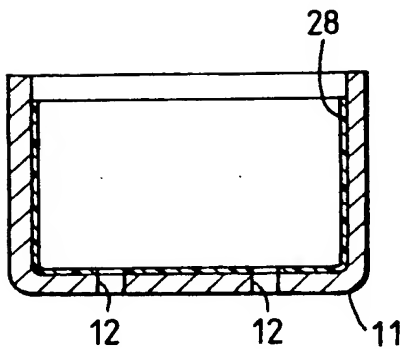


FIG. 4C

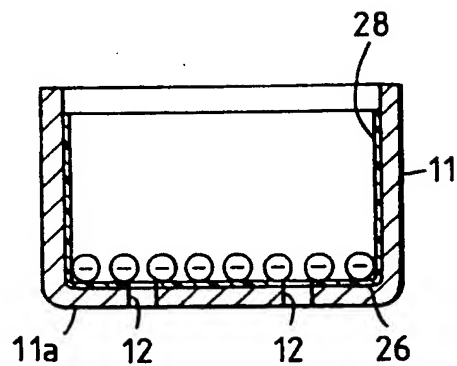
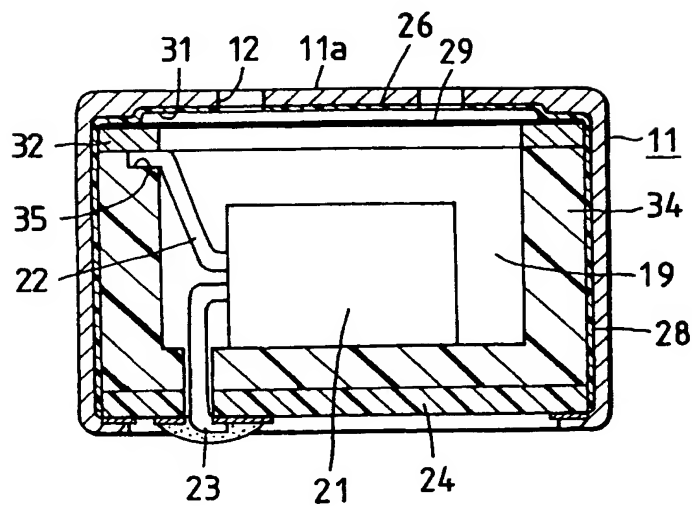


FIG. 5



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FIG. 6

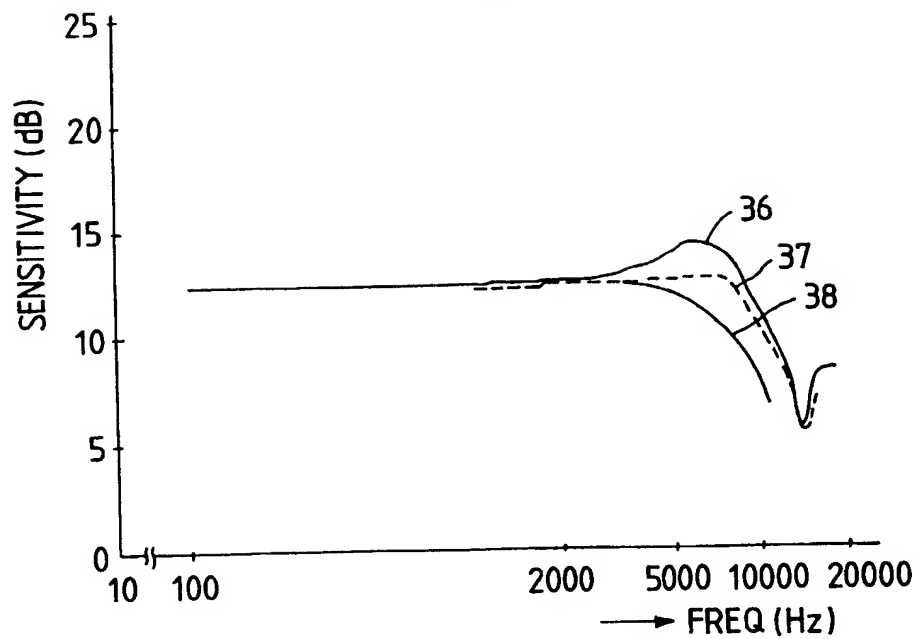
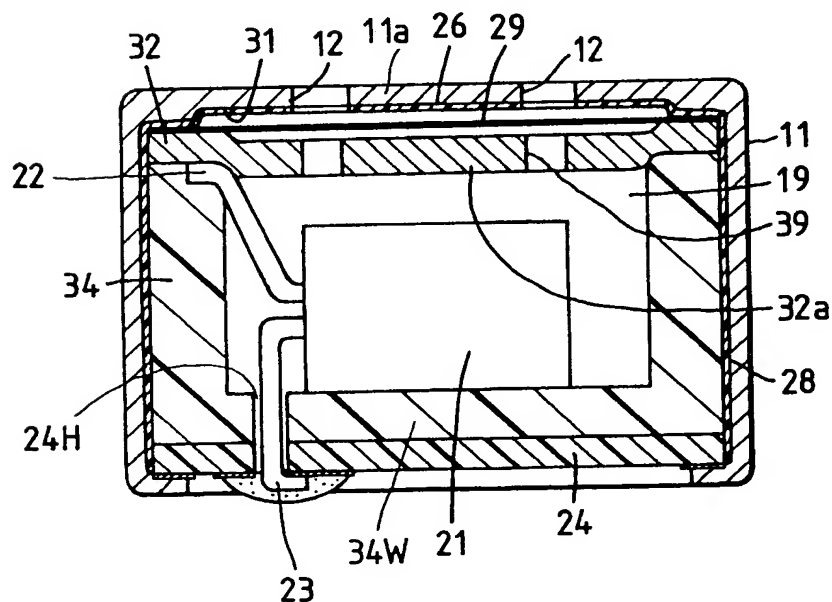


FIG. 7



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FIG. 8A

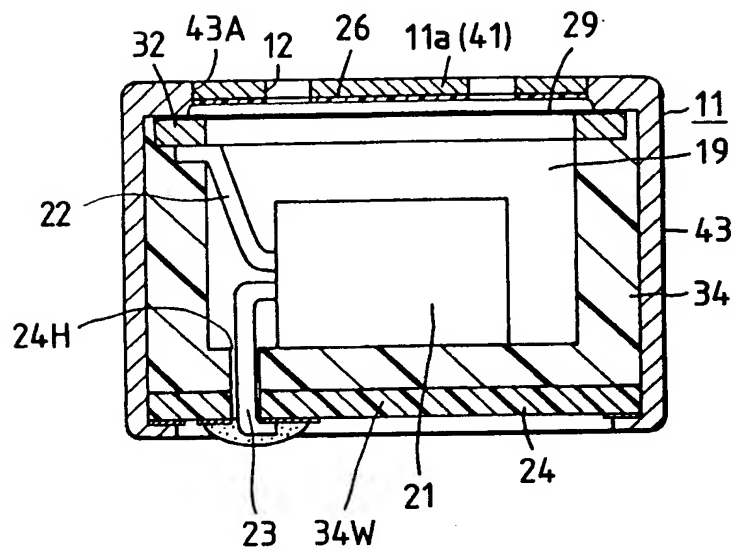
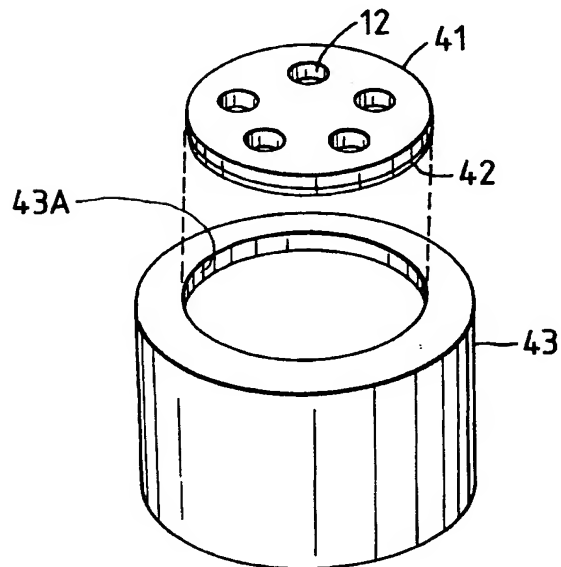


FIG. 8B



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FIG. 9

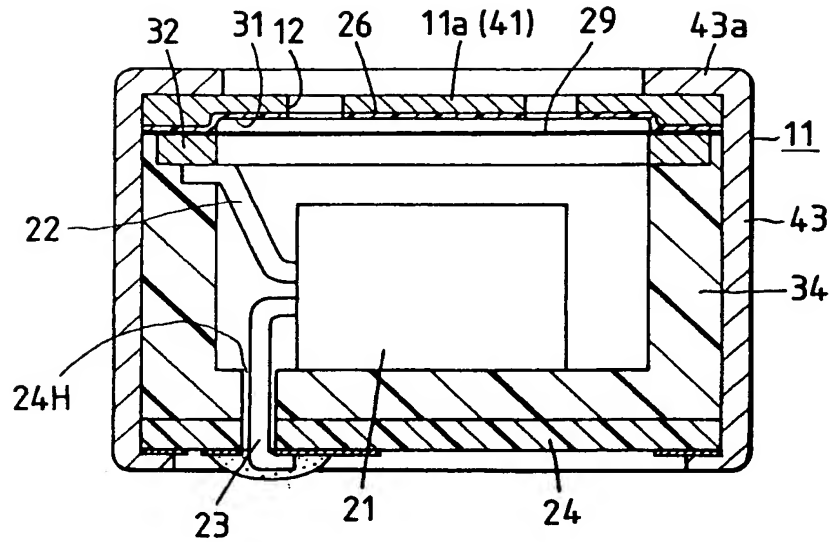


FIG. 10A

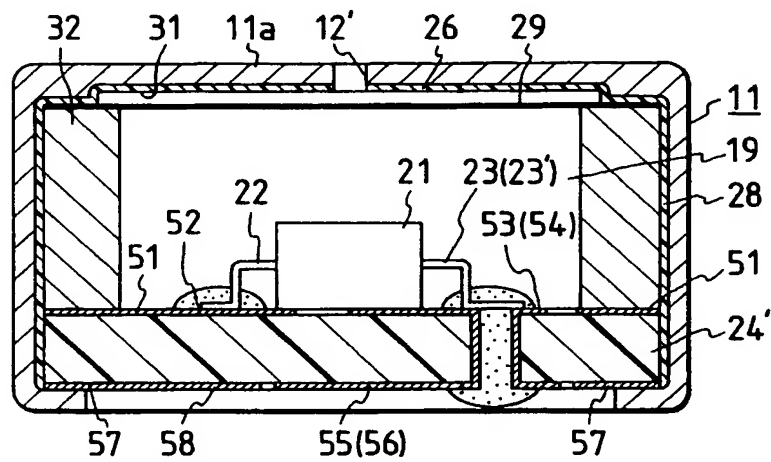


FIG. 10B

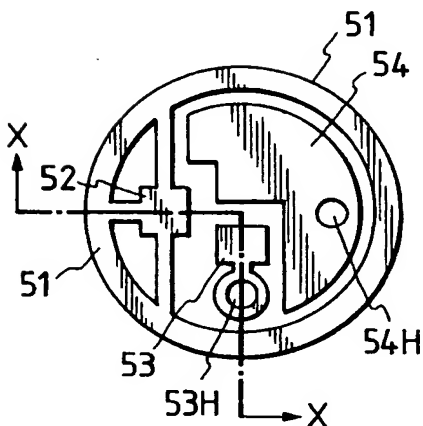


FIG. 10C

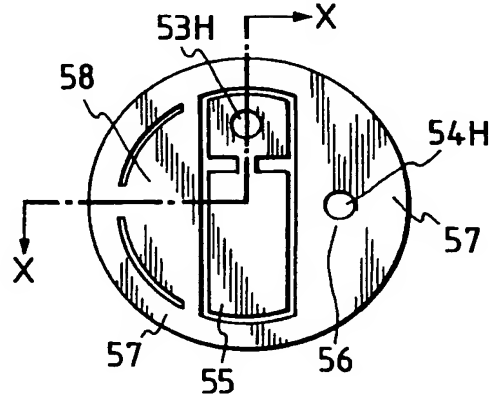


FIG. 11

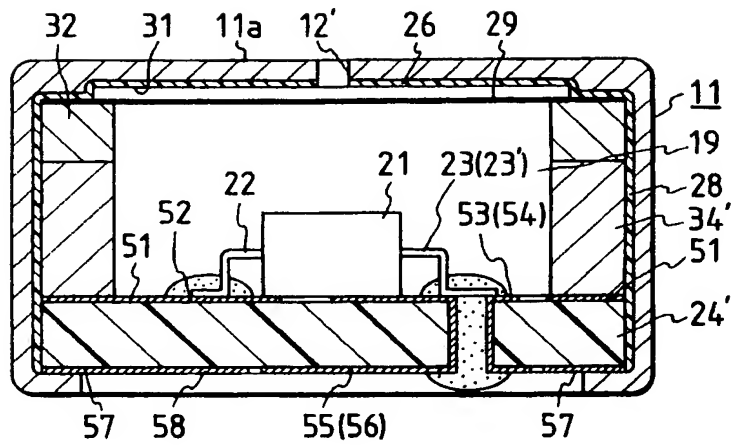


FIG. 12

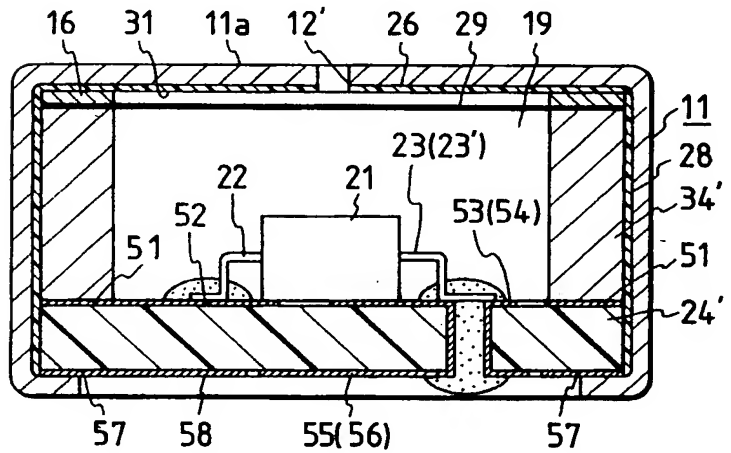


FIG. 13A

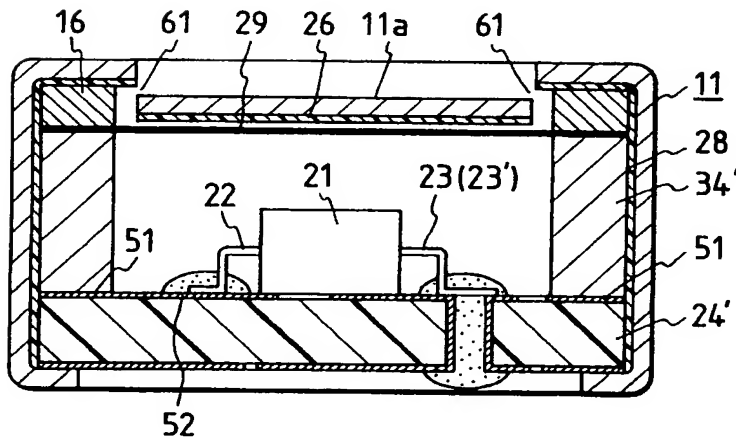
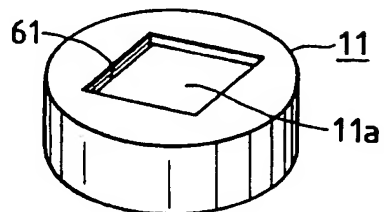


FIG. 13B



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FIG. 14A

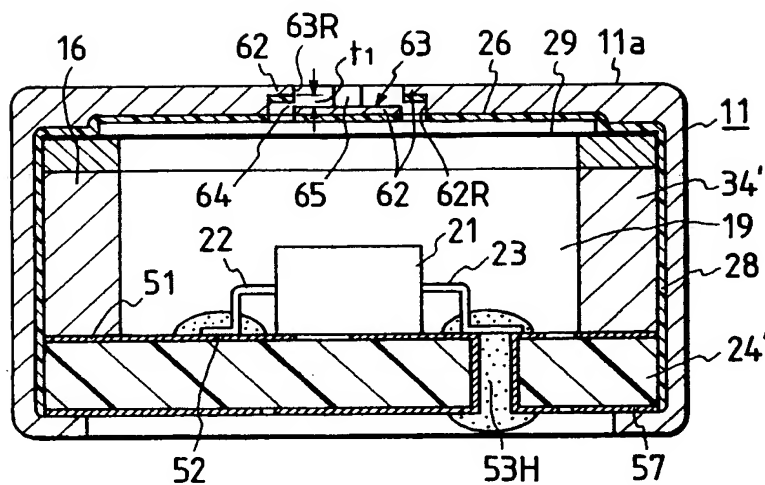
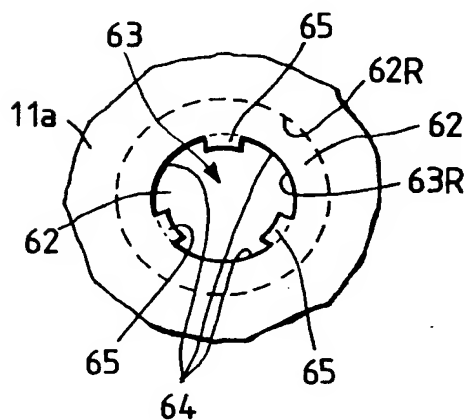


FIG. 14B



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FIG. 15

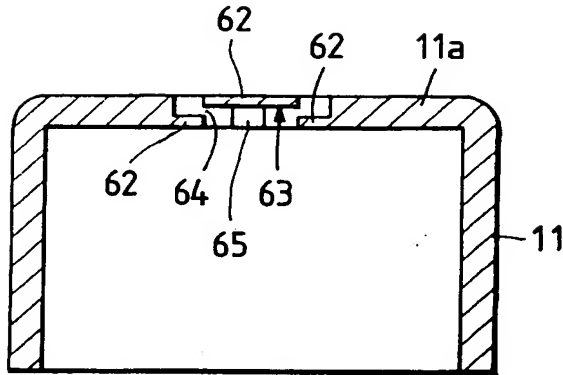


FIG. 16

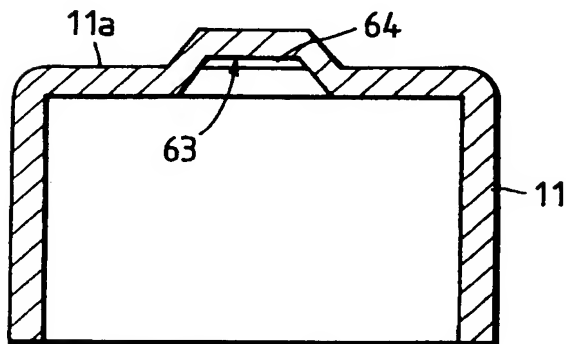
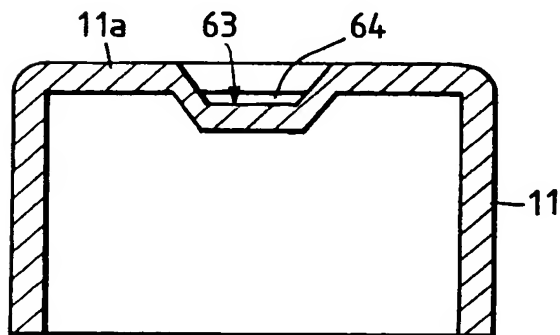


FIG. 17



(19)



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(11) Publication number:

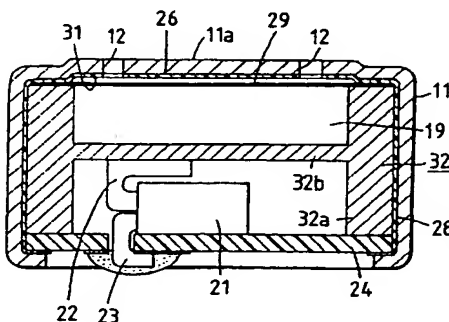
0 531 613 A3

(12)

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20.01.92 JP 1478/92 U(43) Date of publication of application:
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DE FR GB(88) Date of deferred publication of the search report:
24.11.93 Bulletin 93/47(71) Applicant: **HOSIDEN CORPORATION**
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Bahnhofstrasse 103
D-82166 Gräfelfing (DE)(54) **Electret condenser microphone unit.**

(57) A n electret film (26) is formed on the rear side of a front face plate (11a) of a cylindrical capsule (11) made of aluminium. Closely in opposition thereto, an electrically conductive diaphragm (29) is held by an electrically conductive holding member (32) itself and disposed. By means of a wiring board (24)

provided behind the holding member, the rear end of the capsule is closed. The rear end of the capsule is bent on the rear periphery of the wiring board, and caked thereat. In the capsule, an impedance conversion IC device (21) is connected to the electrically conductive holding member and the wiring board.

FIG. 3



European Patent
Office

EUROPEAN SEARCH REPORT

Application Number

EP 92 10 6823

DOCUMENTS CONSIDERED TO BE RELEVANT

Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl.5)
A	US-A-4 117 275 (MIYANAGA ET AL.) * column 1, line 37 - line 48 * * column 1, line 63 - column 3, line 32 * ----	1-17	H04R19/01 H04R19/04
A	EP-A-0 371 620 (MATSUSHITA) * column 4, line 36 - column 5, line 31 * * column 7, line 42 - column 10, line 45 * ----	1,3-16, 18,19	
A	DE-A-3 013 160 (HOSIDEN) * page 11, line 6 - page 12, line 28 * -----	1-16	
			TECHNICAL FIELDS SEARCHED (Int. Cl.5)
			H04R
The present search report has been drawn up for all claims			
Place of search	Date of completion of the search	Examiner	
THE HAGUE	30 SEPTEMBER 1993	ZANTI P.V.L.	
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